Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS**

1. **A**
2. **B**
3. **C**
4. **G2A**
5. **G2B**
6. **G1**
7. **Y7**
8. **GND**
9. **Y6**
10. **Y5**
11. **Y4**
12. **Y3**
13. **Y2**
14. **Y1**
15. **Y0**
16. **VCC**

**.056”**

**9**

**8**

**7**

**.067”**

**9**

**8**

**7**

**HC**

**138G**

**DIE ID**

**14 13 12 11**

**3 4 5 6**

**10**

**9**

**8**

**7**

**15**

**16**

**1**

**2**

**1**

**9**

**8**

**7**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref: HC138G**

**APPROVED BY: DK DIE SIZE .056” X .067” DATE: 7/11/22**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54HC138**

**DG 10.1.2**

#### Rev B, 7/19/02